	CONNECTING CONNECTING CS INDUSTRIES International and Par	PC, Bannockt	ourn, Illinois. A	All rights reserved untions.	under both	This docume level parts, t	ent is a declara he declaration	tion of t encomp	he substance basses all low	s within the er level ma	e manufactur terials for wi	er listed ite hich the m	em. Note: i anufacture	if the item is an as or has engineering	sembly with low responsibility.
752-21.1					Form Type Distribute					neous Materi	erials and Mfg Information				
upplie	r Information														
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*				
nsemi											2025-07-07				
ontact N	lame	Title - Contact]	Phone - Contact*				Email - Contact*					
Product-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*	Title - Representative]	Phone - Representative*				Email - Representative*					
roduct-I	Env-Stewards	Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Dat	e Vers	Version Manufacturing Site		v	Veight*	UOM	Unit Type	
		AFGY100T65SPD FS3 IGBT 650V/1 Diode			100A and Auto	Stealth	2025-07-07	5-07-07 CPA			5	544.59	mg	Each	
Ianufa	cturing Proccess Informa	tion													
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-02		J-STD-020 MSL	Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperatu	ire Numl	ber of Reflow Cyc	eles	
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30		second	ls 3					
omments	8														
or more	information regarding material	composition	please refer t	o page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	12.65	mg	Supplier	Silicon (Si)	7440-21-3		12.65	mg
Die Attach Solder	20.87	mg	Supplier	Silver (Ag)	7440-22-4		0.5218	mg
			А	Lead (Pb)	7439-92-1	7a	19.3048	mg
			Supplier	Tin (Sn)	7440-31-5		1.0435	mg
lead Frame	3643.9	mg	Supplier	Zinc (Zn)	7440-66-6		1.4576	mg
			В	Nickel (Ni)	7440-02-0		119.1555	mg
			Supplier	Iron (Fe)	7439-89-6		2.1863	mg
			Supplier	Copper (Cu)	7440-50-8		3520.0071	mg
			Supplier	Phosphorus (P)	7723-14-0		1.0932	mg
Mold Compound-Black	1759.15	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		87.9575	mg
			Supplier	Proprietary	Proprietary Data		87.9575	mg
			Supplier	Carbon Black (C)	1333-86-4		8.7957	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		79.1618	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		1319.3625	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		87.9575	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		87.9574	mg
Plating	77.82	mg	Supplier	Tin (Sn)	7440-31-5		77.82	mg
Wire Bond - Al	30.2	mg	Supplier	Aluminum (Al)	7429-90-5		30.2	mg